

2A, 200V-1000V Fast Recovery Surface Mount Rectifiers

FEATURES

- Glass passivated junction chip
- Ideal for automated placement
- Low power loss, high efficiency
- Fast switching for high efficiency
- Low profile package
- Moisture sensitivity level: level 1, per J-STD-020
- RoHS Compliant
- Halogen-free according to IEC 61249-2-21

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- High frequency rectification
- Freewheeling application
- Switching mode converters and inverters, computer and telecommunication.

MECHANICAL DATA

- Case: Thin SMA
- Molding compound meets UL 94V-0 flammability rating
- Terminal: Pure tin plated leads, solderable per J-STD-002
- Meet JESD 201 class 2 whisker test
- Polarity: As marked
- Weight: 0.029 g (approximately)

KEY PARAMETERS				
PARAMETER	VALUE	UNIT		
I _F	2	Α		
V_{RRM}	200 -1000	V		
I _{FSM}	50	Α		
T _{J MAX}	150	°C		
Package	Thin SMA			
Configuration	Single Die			









Thin SMA

ABSOLUTE MAXIMUM RATINGS (T _A = 25°C unless otherwise noted)								
PARAMETER		SYMBOL	RS2DAL	RS2GAL	RS2JAL	RS2KAL	RS2MAL	UNIT
Marking code on the devi	ce		RS2DAL	RS2GAL	RS2JAL	RS2KAL	RS2MAL	
Repetitive peak reverse v	oltage	V_{RRM}	200	400	600	800	1000	V
Reverse voltage, total rms value		V _{R(RMS)}	140	280	420	560	700	V
Forward current		I _F	2				Α	
Surge peak forward current, single half sine-	8.3ms at T _A = 25°C		50				Α	
wave superimposed on rated load per diode	1.0ms at T _A = 25°C	I _{FSM}	140				Α	
Junction temperature		TJ	-55 to +150				°C	
Storage temperature		T _{STG}	-55 to +150			°C		

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THERMAL PERFORMANCE					
PARAMETER	SYMBOL	TYP	UNIT		
Junction-to-lead thermal resistance	$R_{\Theta JL}$	16	°C/W		
Junction-to-ambient thermal resistance	R _{OJA}	73	°C/W		
Junction-to-case thermal resistance	R _{OJC}	14	°C/W		

Thermal Performance Note: Units mounted on PCB (5mm x 5mm Cu pad test board)

PARAMET	ER	CONDITIONS	SYMBOL	TYP	MAX	UNIT
		I _F = 1.0A, T _J = 25°C		0.93	-	V
	RS2DAL	I _F = 2.0A, T _J = 25°C		1.01	1.30	V
	RS2GAL RS2JAL	I _F = 1.0A, T _J = 125°C		0.78	-	V
Famuurd valtaga (1)		I _F = 2.0A, T _J = 125°C		0.88	1.02	V
Forward voltage ⁽¹⁾		I _F = 1.0A, T _J = 25°C	V _F	0.98	-	V
	RS2KAL	I _F = 2.0A, T _J = 25°C		1.06	1.30	V
	RS2MAL	I _F = 1.0A, T _J = 125°C		0.83	-	V
		I _F = 2.0A, T _J = 125°C		0.93	1.05	V
Reverse current @ rated V _R ⁽²⁾		T _J = 25°C	1	-	1	μΑ
		T _J = 125°C	- I _R	-	40	μΑ
	RS2DAL RS2GAL		t _{rr}	-	150	ns
Reverse recovery time	RS2JAL	I _F =0.5A,I _R =1.0A, Irr=0.25A		-	250	ns
	RS2KAL RS2MAL	0.2071		-	500	ns
Junction capacitance	RS2DAL RS2GAL RS2JAL	1 MHz, V _R =4.0V	CJ	11	-	pF
	RS2KAL RS2MAL			10	-	pF

Notes:

- (1) Pulse test with PW=0.3 ms
- (2) Pulse test with PW=30 ms

ORDERING INFORMATION					
ORDERING CODE ⁽¹⁾	PACKAGE	PACKING			
RS2xAL M3G	Thin SMA	3,500 / 7" reel			
RS2xAL M2G	Thin SMA	14,000 / 13" reel			

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Notes:

(1) "x" defines voltage from 200V(RS2DAL) to 1000V(RS2MAL)



CHARACTERISTICS CURVES

 $(T_A = 25^{\circ}C \text{ unless otherwise noted})$

Fig.1 Forward Current Derating Curve

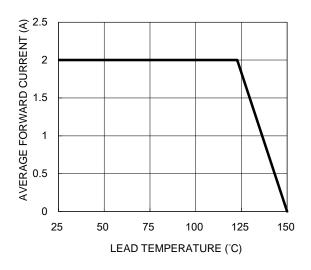


Fig.3 Typical Reverse Characteristics

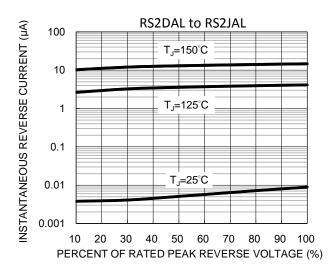


Fig.5 Typical Reverse Characteristics

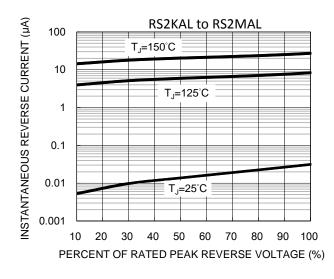


Fig.2 Typical Junction Capacitance

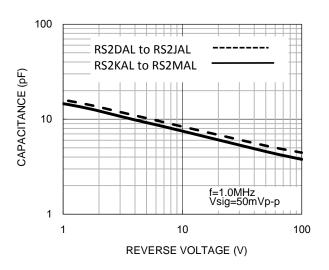


Fig.4 Typical Forward Characteristics

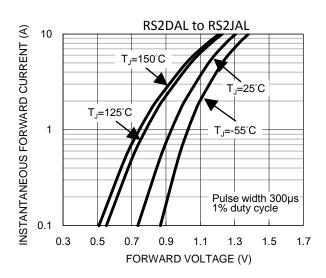
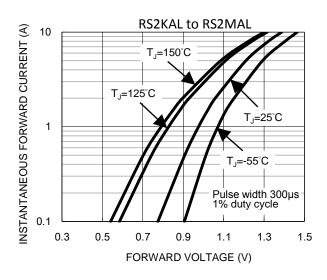


Fig.6 Typical Forward Characteristics





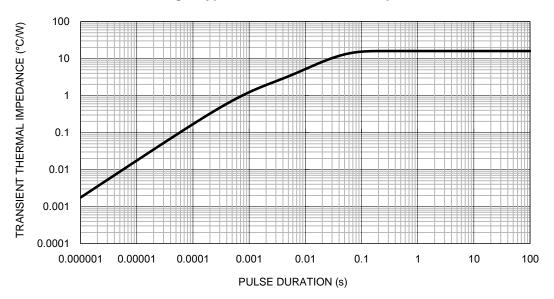
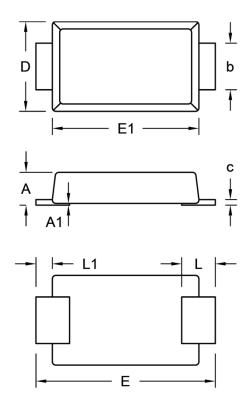


Fig.7 Typical Transient Thermal Impedance



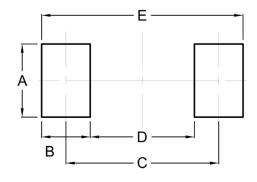
PACKAGE OUTLINE DIMENSIONS

Thin SMA



DIM.	Unit	(mm)	Unit (inch)		
Dilvi.	Min.	Max.	Min.	Max.	
Α	0.90	1.00	0.035	0.039	
A1	0.00	0.10	0.000	0.004	
b	1.25	1.45	0.049	0.057	
С	0.10	0.22	0.004	0.009	
D	2.50	2.70	0.098	0.106	
E	5.05	5.35	0.199	0.211	
E1	4.15	4.35	0.163	0.171	
L	0.75	1.20	0.030	0.047	
L1	0.30	0.60	0.012	0.024	

SUGGESTED PAD LAYOUT



Symbol	Unit (mm)	Unit (inch)
Α	2.10	0.083
В	1.40	0.055
С	4.40	0.173
D	3.00	0.118
E	5.80	0.228

MARKING DIAGRAM



P/N = Marking Code YW = Date Code F = Factory Code



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